

L Number	Hits	Search Text	DB	Time stamp
1	292878	conferenc\$3 teleconferenc\$3 meeting collaborat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:27
2	254032	login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:29
3	2868995	conferee participant member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:30
4	9975	(login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) with (conferee participant member)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:31
5	39218	(material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:32
6	125156	(material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation) same (semiconductor chip ic (integrated adj1 circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:37
7	7	(conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and ((login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) with (conferee participant member)) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation) same (semiconductor chip ic (integrated adj1 circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:35
8	1554962	(material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:40
9	1313	(conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:41
10	766007	(design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:09

11	431	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:43
12	307	((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:45
13	52	(((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 20:45
14	52	(((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and chat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:39
15	52	((((((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) and (login log-in password (access\$3 near3 (control permi\$5 security)) authenticat\$3) and (conferee participant member) and ((material document project) with ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) discussion)) and ((material document project) same (design\$3 manufacturing fabricat\$3 product performance evaluation))) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and sale) and (chat chatroom)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:05
16	0	20040205644.URPN.	USPAT	2004/11/07 21:05

17	36	((("20020156929" or ("20040205644" or ("20040107256" or ("20040107249" or ("20040107125" or ("20040103040" or ("20030192029" or ("20030154387" or ("20030152904" or ("20030126033" or ("20030120557" or ("20030023686" or ("20020184191" or ("20010042030" or ("6615166" or ("6611822" or ("6581039" or ("6571235" or ("5867494"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:09
18	21	((("20020156929" or ("20040205644" or ("20040107256" or ("20040107249" or ("20040107125" or ("20040103040" or ("20030192029" or ("20030154387" or ("20030152904" or ("20030126033" or ("20030120557" or ("20030023686" or ("20020184191" or ("20010042030" or ("6615166" or ("6611822" or ("6581039" or ("6571235" or ("5867494"))).PN.) and ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:09
19	3577	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) same ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:38
20	3560	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) with ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:38
21	4959	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) same ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit)))) ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) with ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:39
22	14	((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) same ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor chip ic (integrated adj1 circuit)))) ((conferenc\$3 teleconferenc\$3 meeting collaborat\$3) with ((design\$3 manufacturing fabricat\$3 product performance evaluation) with (semiconductor circuit chip ic (integrated adj1 circuit)))) and (chat chatroom)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/07 21:39